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Abstract

Method for Connecting An Integrated Circuit to A Substrate and Corresponding Circuit Arrangement

The present invention provides a method for connecting an integrated circuit (1), in particular of a chip or a wafer or a hybrid, to a substrate (30), which has the following steps: provision of a first electrical contact structure (3, 4) on a first main area (HF1) of the integrated circuit (1); provision of a corresponding second electrical contact structure (33) on an upper side (OS) of the substrate (30); at least one of the first and second electrical contact structures (3, 4; 33) having elastic elevations (3); attachment of a second main area (HF2) of the integrated circuit (1) to a frame structure (20, 22); placement of the first electrical contact structure (3, 4) onto the second electrical contact structure (33), so that the two are in electrical contact; and attachment of the frame structure (20, 22) to the substrate (30) in such a way that the elastic elevations (3) are under compressive stress. The invention likewise provides a corresponding circuit arrangement.

(Figure 2c)



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